Patent claims

1. Electrically conductive, thermoplastic and heat-activatable adhesive film, comprising

i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,

ii) one or more tackifying resins in a proportion of from 5 to 50% by weight and/or

iii) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, and

iv) silver-coated glass beads or silver particles in a proportion of from 0.1 to 40% by weight,

v) where the diameter of the glass beads is at least equal to the thickness of the adhesive film.

2. Adhesive film according to Claim 1, characterized in that the thermoplastic polymer comprises thermoplastic polyolefins, polyesters, polyurethanes or polyamides or modified rubbers, such as nitrile rubbers in particular.

3. Adhesive film according to Claims 1 and 2, characterized in that the adhesive film is blended with one or more additives, such as colorants, mineral or organic fillers, such as silica, carbon powders and metal powders.

4. Thermoplastic adhesive film according to Claims 1 to 3, characterized in that the adhesive film has a thickness of from 20 to 500 μm.

5. Thermoplastic adhesive film according to Claims 1 to 4, characterized in that the adhesive film is suitable for hot pressing at temperatures below 120°C, in particular from 80 to 100°C.

6. Thermoplastic adhesive film according to Claims 1 to 5, characterized in that the adhesive film has the same dimensions as the module and is in the form of a punched film section.

7. Use of an adhesive film according to one of Claims 1 to 6 for implanting electrical modules in a card body provided with a cutout for accommodating an electronic module which on the first side has a plurality of contact surfaces and on the second side, which is opposite the first side, has an IC chip whose terminals are connected via electrical conductors to the contact surfaces, the adhesive film being used to connect the second side of the module to the card body.

8. Use of an adhesive ~~film~~ according to one of Claims 1 to 6 for structural bonding, with or without ~~subsequent~~ heat-curing.

ADD A1

ADD B3